



Material Content Data Sheet



Sales Product Name		TLE42764GV		Issued		25. January 2018		
MA#		MA001151146						
Package		PG-TO263-5-1		Weight*		1673.71 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.179	0.19	0.19	1899	1899
leadframe	inorganic material	phosphorus	7723-14-0	0.145	0.01		87	
	non noble metal	iron	7439-89-6	0.483	0.03		288	
	non noble metal	copper	7440-50-8	482.096	28.80	28.84	288041	288416
	non noble metal	aluminium	7429-90-5	0.275	0.02	0.02	164	164
wire	non noble metal	aluminium	7429-90-5	0.275	0.02	0.02	164	164
encapsulation	organic material	carbon black	1333-86-4	1.456	0.09		870	
	plastics	epoxy resin	-	66.987	4.00		40023	
	inorganic material	silicondioxide	60676-86-0	659.679	39.40	43.49	394141	435034
leadfinish	non noble metal	tin	7440-31-5	12.370	0.74	0.74	7391	7391
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.243	0.01	0.01	145	146
solder	non noble metal	tin	7440-31-5	0.095	0.01		57	
	noble metal	silver	7440-22-4	0.119	0.01		71	
	non noble metal	lead	7439-92-1	4.552	0.27	0.29	2720	2848
heatspreader	inorganic material	phosphorus	7723-14-0	0.133	0.01		79	
	non noble metal	iron	7439-89-6	0.442	0.03		264	
	non noble metal	copper	7440-50-8	441.456	26.38	26.42	263759	264102
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com